TOSHIBA Transistor Silicon PNP / NPN Epitaxial Type (PCT Process)

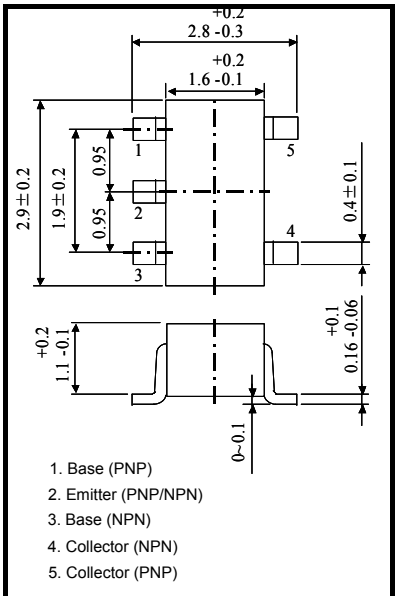
HN4B101J

MOS Gate Drive Applications

Switching Applications

- Small footprint due to a small and thin package
- High DC current gain : h_{FE} = 200 to 500 (I_C = −0.12 A)
- Low collector-emitter saturation: PNP $V_{CE\ (sat)}$ = −0.20 V (max)
  : NPN $V_{CE\ (sat)}$ = 0.17 V (max)
- High-speed switching : PNP t_f = 45 ns (typ.)
  : NPN t_f = 50 ns (typ.)

Unit: mm



JEDEC	—
JEITA	—
TOSHIBA	2-3L1A

Weight: 0.014g (typ.)

Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating		Unit
			PNP	NPN	
Collector-base voltage		V_{CBO}	−30	50	V
Collector-emitter voltage		V_{CEO}	−30	30	V
Emitter-base voltage		V_{EBO}	−7	7	V
Collector current	DC (Note 1)	I_C	−1.0	1.2	A
	Pulse (Note 1)	I_{CP}	−5.0	5.0	
Base current		I_B	−120	120	mA
Collector power dissipation (t = 10 s)	Single-device operation	P_C (Note 2)	0.85		W
Collector power dissipation (DC)	Single-device operation	P_C (Note 2)	0.55		W
Junction temperature		T_j	150		°C
Storage temperature range		T_{stg}	−55 to 150		°C

Note 1: Ensure that the channel temperature does not exceed 150°C during use of the device.

Note 2: Mounted on an FR4 board (glass-epoxy; 1.6 mm thick; Cu area, 645 mm^2)

Note 3: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Start of commercial production
2004-10

Figure 1. Circuit Configuration (top view)

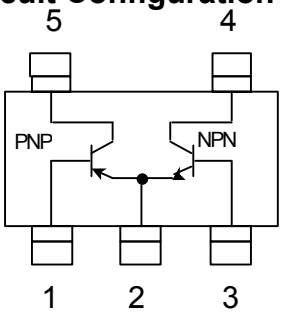
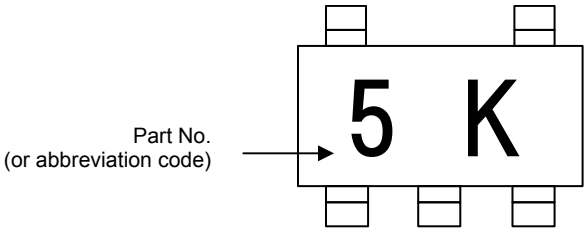


Figure 2. Marking



Electrical Characteristics (Ta = 25°C)

PNP

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Collector cut-off current		I_{CBO}	V_{CB} = −30 V, I_E = 0	—	—	−100	nA
Emitter cut-off current		I_{EBO}	V_{EB} = −7 V, I_C = 0	—	—	−100	nA
Collector-emitter breakdown voltage		$V_{(BR)\ CEO}$	I_C = −10 mA, I_B = 0	−30	—	—	V
DC current gain		h_{FE} (1)	V_{CE} = −2 V, I_C = −0.12 A	200	—	500	
		h_{FE} (2)	V_{CE} = −2 V, I_C = −0.4 A	125	—	—	
Collector-emitter saturation voltage		$V_{CE\ (sat)}$	I_C = −0.4 A, I_B = −13 mA	—	—	−0.20	V
Base-emitter saturation voltage		$V_{BE\ (sat)}$	I_C = −0.4 A, I_B = −13 mA	—	—	−1.10	V
Collector output capacitance		C_{ob}	V_{CB} = −10 V, I_E = 0, f = 1MHz	—	7.8	—	pF
Switching time	Rise time	t_r	See Figure 3 circuit diagram $V_{CC} \simeq$ −16 V, R_L = 40 Ω $-I_{B1} = I_{B2}$ = 13 mA	—	40	—	ns
	Storage time	t_{stg}		—	200	—	
	Fall time	t_f		—	45	—	

NPN

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Collector cut-off current		I_{CBO}	V_{CB} = 50 V, I_E = 0	—	—	100	nA
Emitter cut-off current		I_{EBO}	V_{EB} = 7 V, I_C = 0	—	—	100	nA
Collector-emitter breakdown voltage		$V_{(BR)\ CEO}$	I_C = 10 mA, I_B = 0	30	—	—	V
DC current gain		h_{FE} (1)	V_{CE} = 2 V, I_C = 0.12 A	200	—	500	
		h_{FE} (2)	V_{CE} = 2 V, I_C = 0.4 A	125	—	—	
Collector-emitter saturation voltage		$V_{CE\ (sat)}$	I_C = 0.4 A, I_B = 13 mA	—	—	0.17	V
Base-emitter saturation voltage		$V_{BE\ (sat)}$	I_C = 0.4 A, I_B = 13 mA	—	—	1.10	V
Collector output capacitance		C_{ob}	V_{CB} = 10 V, I_E = 0, f = 1MHz	—	7.0	—	pF
Switching time	Rise time	t_r	See Figure 4 circuit diagram $V_{CC} \simeq$ 16 V, R_L = 40 Ω $I_{B1} = -I_{B2}$ = 13 mA	—	45	—	ns
	Storage time	t_{stg}		—	450	—	
	Fall time	t_f		—	50	—	

Figure 3. Switching Time Test Circuit & Timing Chart

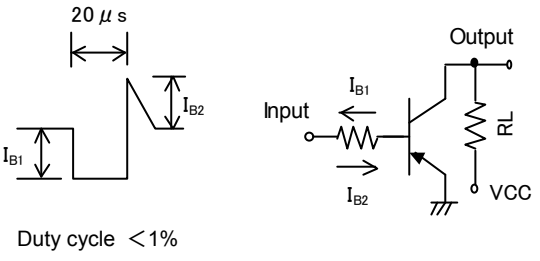
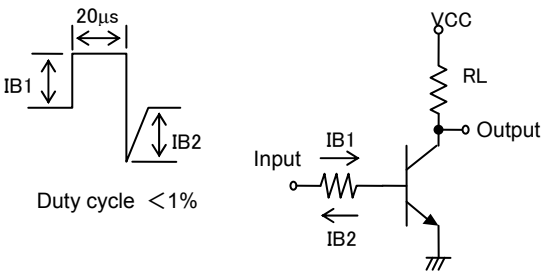
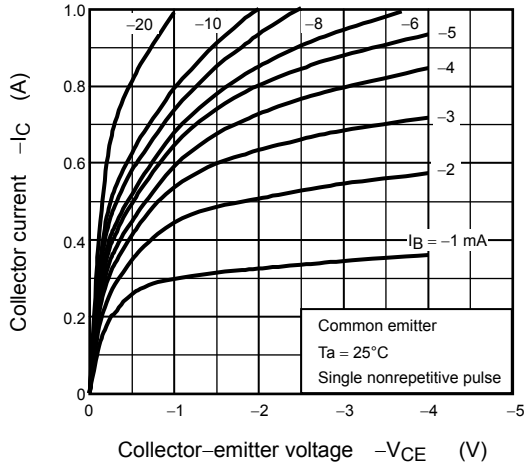


Figure 4. Switching Time Test Circuit & Timing Chart

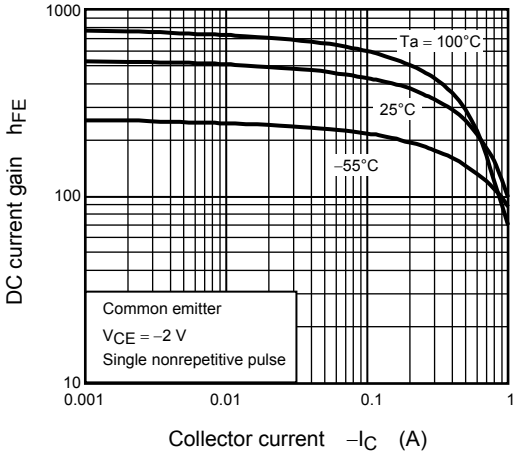


PNP

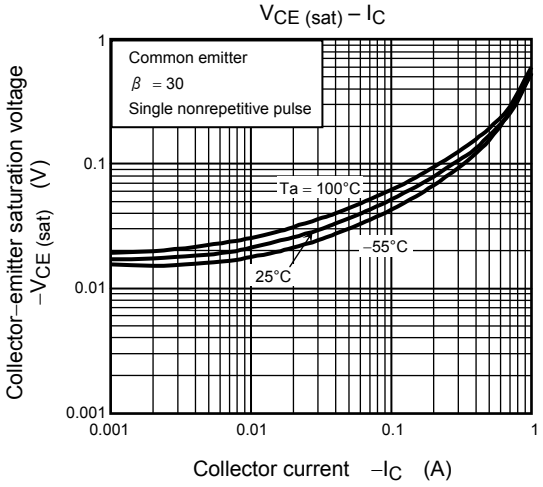
$I_C - V_{CE}$



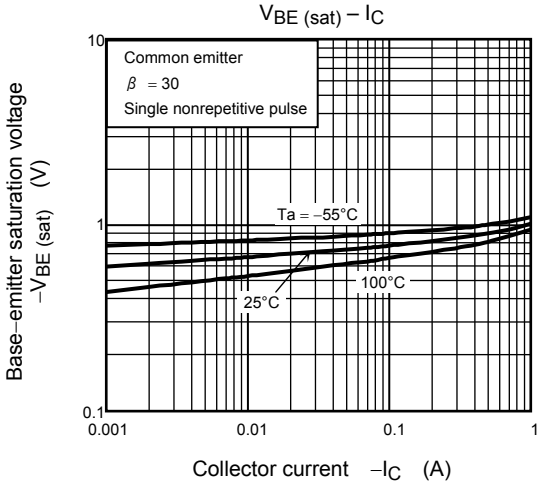
$h_{FE} - I_C$



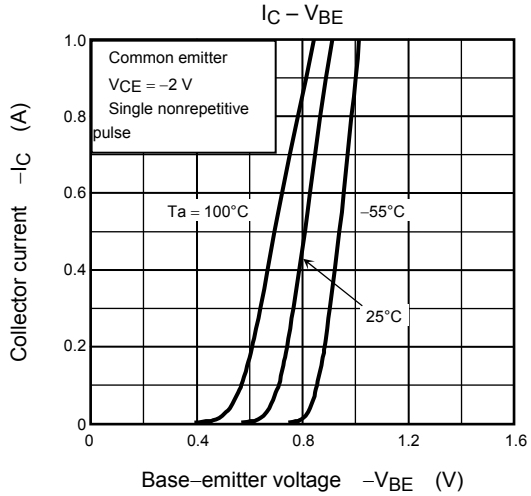
$V_{CE\ (sat)} - I_C$



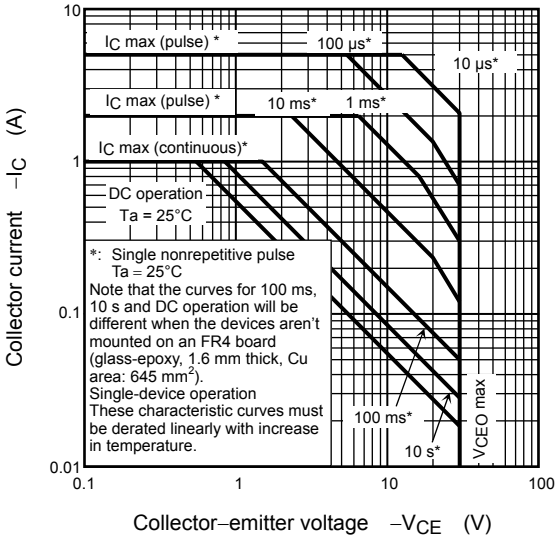
$V_{BE\ (sat)} - I_C$



$I_C - V_{BE}$

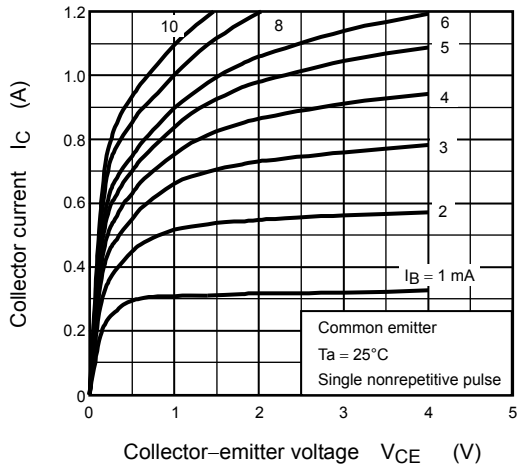


Safe operating area

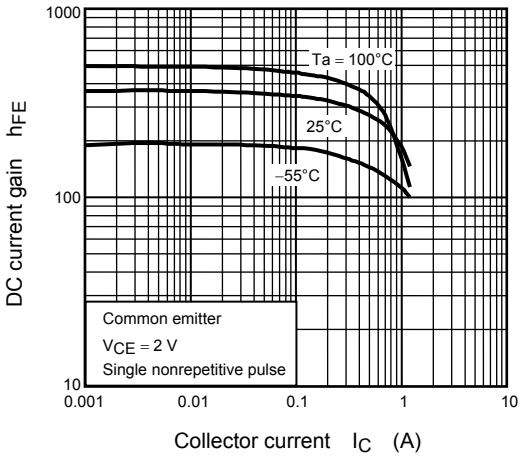


NPN

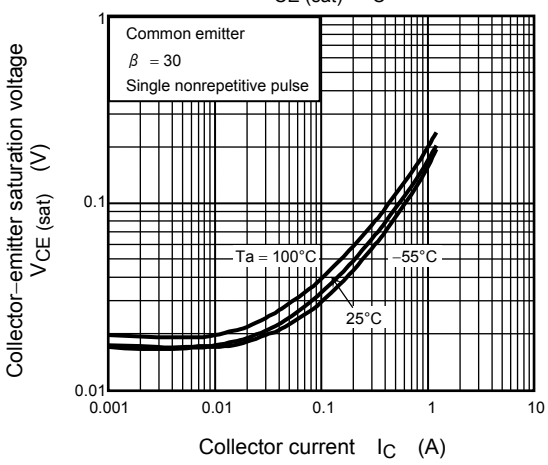
$I_C - V_{CE}$



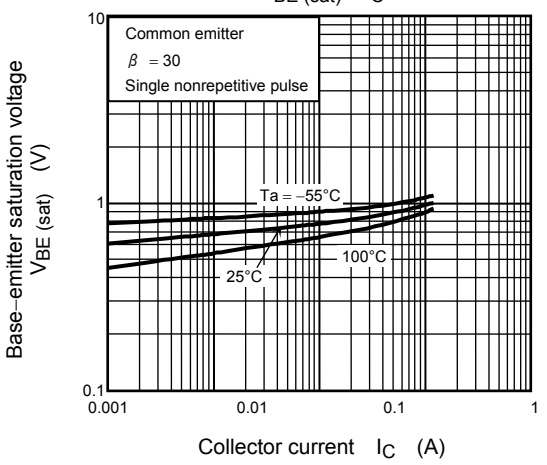
$h_{FE} - I_C$



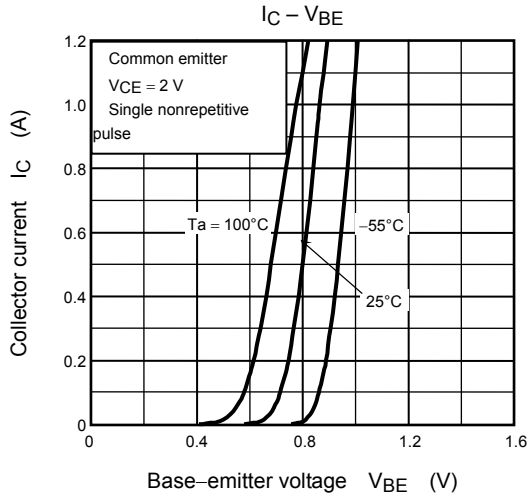
$V_{CE\ (sat)} - I_C$



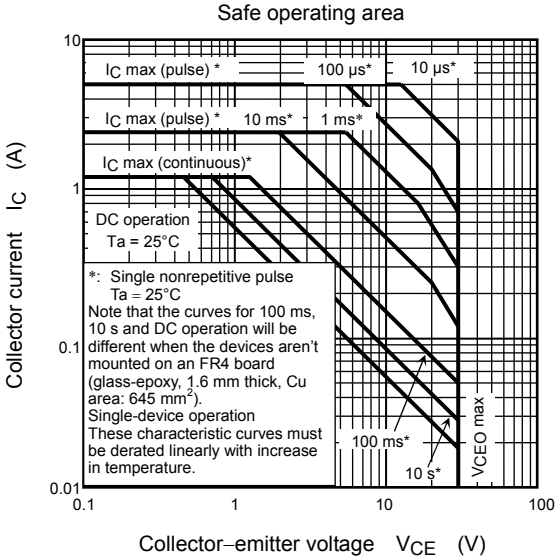
$V_{BE\ (sat)} - I_C$



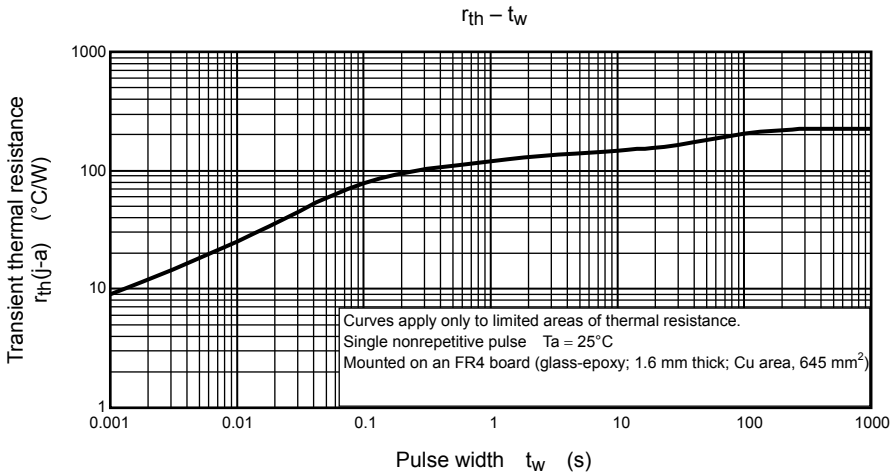
$I_C - V_{BE}$

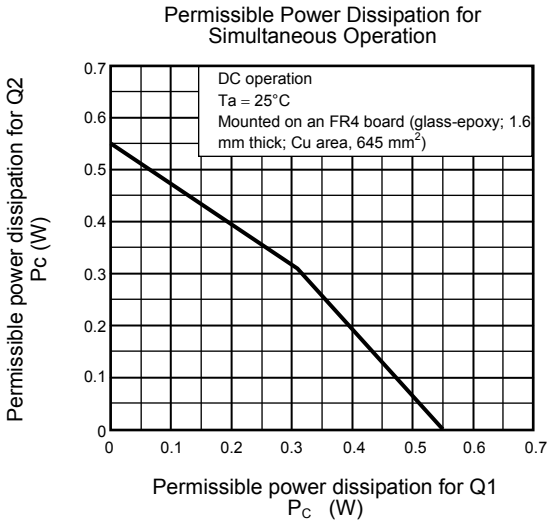


Safe operating area



Common





Collector power dissipation at single-device operation is 0.55 W.
Collector power dissipation at single-device value at dual operation is 0.31 W.
Collector power dissipation at dual operation is set to 0.62 W.

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